Complementary Silicon Plastic Power Transistors

Designed for use in general purpose amplifier and switching applications.

Features

- Epoxy Meets UL 94 V-0 @ 0.125 in
- These Devices are Pb-Free and are RoHS Compliant*

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|-----------------------------------|-----------------------|-----------|
| Collector–Emitter Voltage TIP41G, TIP42G TIP41AG, TIP42AG TIP41BG, TIP42BG TIP41CG, TIP42CG | V _{CEO} | 40 60 80 100 | Vdc |
| Collector-Base Voltage TIP41G, TIP42G TIP41AG, TIP42AG TIP41BG, TIP42BG TIP41CG, TIP42CG | V _{CB} | 40 60 80 100 | Vdc |
| Emitter-Base Voltage | V _{EB} | 5.0 | Vdc |
| Collector Current – Continuous | I _C | 6.0 | Adc |
| Collector Current – Peak | I _{CM} | 10 | Adc |
| Base Current | Ι _Β | 2.0 | Adc |
| Total Power Dissipation @ T _C = 25°C Derate above 25°C | P _D | 65 0.52 | W W/°C |
| Total Power Dissipation @ T _A = 25°C Derate above 25°C | P _D | 2.0 0.016 | W W/°C |
| Unclamped Inductive Load Energy (Note 1) | E | 62.5 | mJ |
| Operating and Storage Junction, Temperature Range | T _J , T _{stg} | -65 to +150 | °C |
| ESD - Human Body Model | HBM | 3B | V |
| ESD - Machine Model | ММ | С | V |

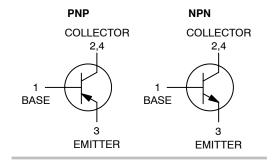
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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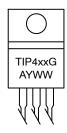
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6 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 40-60-80-100 VOLTS, 65 WATTS





MARKING DIAGRAM



TIP4xx = Device Code xx = 1, 1A, 1B, 1C 2, 2A, 2B, 2C A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

^{1.} I_C = 2.5 A, L = 20 mH, P.R.F. = 10 Hz, V_{CC} = 10 V, R_{BE} = 100 Ω .

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|----------------|------|------|
| Thermal Resistance, Junction-to-Case | $R_{	heta JC}$ | 1.67 | °C/W |
| Thermal Resistance, Junction-to-Ambient | $R_{	heta JA}$ | 57 | °C/W |

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|---|-----------------------|-----------------------|--------------------------|------|
| OFF CHARACTERISTICS | , | | • | • |
| Collector-Emitter Sustaining Voltage (Note 2) (I _C = 30 mAdc, I _B = 0) TIP41G, TIP42G TIP41AG, TIP42AG TIP41BG, TIP42BG TIP41CG, TIP42CG | V _{CEO(sus)} | 40 60 80 100 | - - - - | Vdc |
| Collector Cutoff Current | I _{CEO} | - | 0.7 0.7 | mAdc |
| Collector Cutoff Current $ \begin{aligned} &(V_{CE}=40 \text{ Vdc}, V_{EB}=0) \\ &\text{TIP41G}, \text{TIP42G} \end{aligned} \\ &(V_{CE}=60 \text{ Vdc}, V_{EB}=0) \\ &\text{TIP41AG}, \text{TIP42AG} \end{aligned} \\ &(V_{CE}=80 \text{ Vdc}, V_{EB}=0) \\ &\text{TIP41BG}, \text{TIP42BG} \end{aligned} \\ &(V_{CE}=100 \text{ Vdc}, V_{EB}=0) \\ &\text{TIP41CG}, \text{TIP42CG} \end{aligned}$ | I _{CES} | - - - | 400 400 400 400 | μAdc |
| Emitter Cutoff Current (V _{BE} = 5.0 Vdc, I _C = 0) | I _{EBO} | _ | 1.0 | mAdc |
| ON CHARACTERISTICS (Note 2) | <u> </u> | | | |
| DC Current Gain | h _{FE} | 30 15 | - 75 | - |
| Collector–Emitter Saturation Voltage (I _C = 6.0 Adc, I _B = 600 mAdc) | V _{CE(sat)} | - | 1.5 | Vdc |
| Base-Emitter On Voltage (I _C = 6.0 Adc, V _{CE} = 4.0 Vdc) | V _{BE(on)} | - | 2.0 | Vdc |
| DYNAMIC CHARACTERISTICS | <u>'</u> | | | • |
| Current–Gain – Bandwidth Product (I _C = 500 mAdc, V _{CE} = 10 Vdc, f _{test} = 1.0 MHz) | f _T | 3.0 | - | MHz |
| Small–Signal Current Gain (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 1.0 kHz) | h _{fe} | 20 | - | - |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

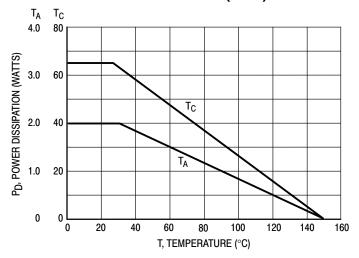
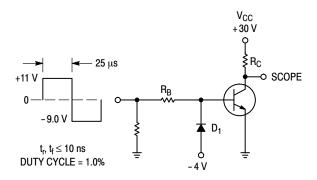


Figure 1. Power Derating



 $\rm R_{\rm B}$ and $\rm R_{\rm C}$ varied to obtain desired current levels

D $_1$ MUST BE FAST RECOVERY TYPE, e.g.: 1N5825 USED ABOVE I $_B\approx 100$ mA MSD6100 USED BELOW I $_B\approx 100$ mA

Figure 2. Switching Time Test Circuit

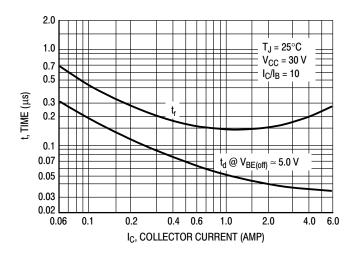


Figure 3. Turn-On Time

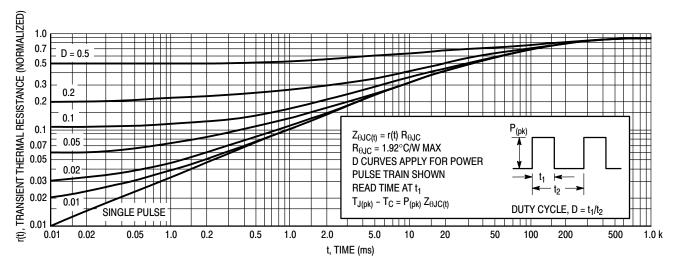


Figure 4. Thermal Response

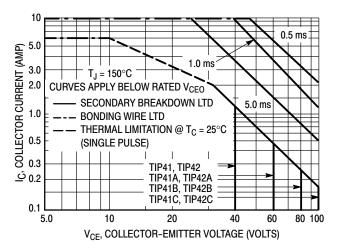


Figure 5. Active-Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)} = 150^{\circ}\text{C}$; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ}\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

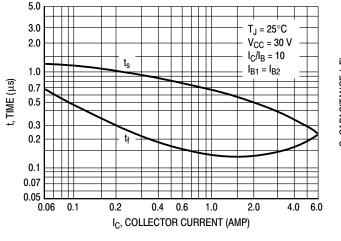


Figure 6. Turn-Off Time

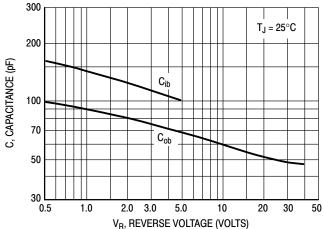


Figure 7. Capacitance

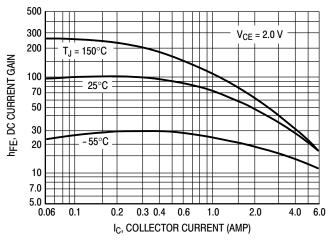


Figure 8. DC Current Gain

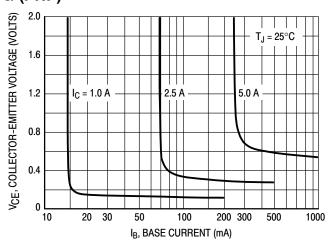


Figure 9. Collector Saturation Region

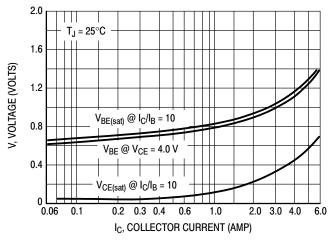


Figure 10. "On" Voltages

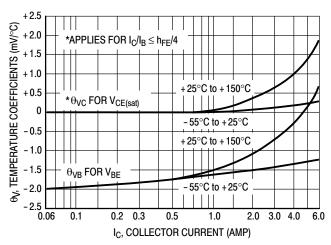


Figure 11. Temperature Coefficients

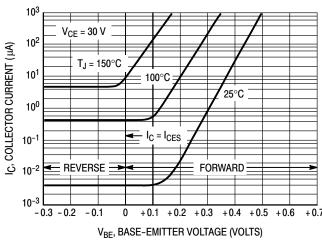


Figure 12. Collector Cut-Off Region

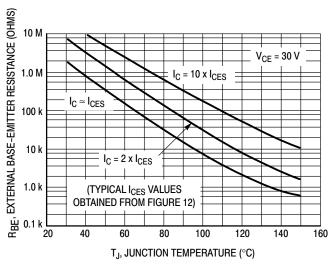
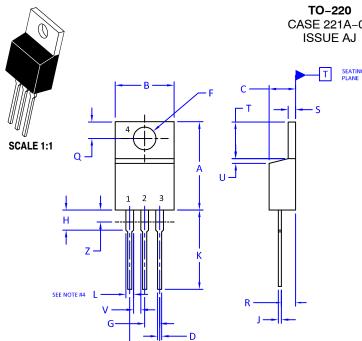


Figure 13. Effects of Base-Emitter Resistance

ORDERING INFORMATION

| Device | Package | Shipping |
|---------|---------------------|-----------------|
| TIP41G | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP41AG | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP41BG | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP41CG | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP42G | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP42AG | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP42BG | TO-220 (Pb-Free) | 50 Units / Rail |
| TIP42CG | TO-220 (Pb-Free) | 50 Units / Rail |

MECHANICAL CASE OUTLINE



CASE 221A-09

DATE 05 NOV 2019

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

4. MAX WIDTH FOR F102 DEVICE = 1.35MM

| | INCHES | | MILLIMETERS | | |
|-----|--------|-------|-------------|-------|--|
| DIM | MIN. | MAX. | MIN. | MAX. | |
| Α | 0.570 | 0.620 | 14.48 | 15.75 | |
| В | 0.380 | 0.415 | 9.66 | 10.53 | |
| С | 0.160 | 0.190 | 4.07 | 4.83 | |
| D | 0.025 | 0.038 | 0.64 | 0.96 | |
| F | 0.142 | 0.161 | 3.60 | 4.09 | |
| G | 0.095 | 0.105 | 2.42 | 2.66 | |
| Н | 0.110 | 0.161 | 2.80 | 4.10 | |
| J | 0.014 | 0.024 | 0.36 | 0.61 | |
| К | 0.500 | 0.562 | 12.70 | 14.27 | |
| L | 0.045 | 0.060 | 1.15 | 1.52 | |
| N | 0.190 | 0.210 | 4.83 | 5.33 | |
| Q | 0.100 | 0.120 | 2.54 | 3.04 | |
| R | 0.080 | 0.110 | 2.04 | 2.79 | |
| S | 0.045 | 0.055 | 1.15 | 1.41 | |
| Т | 0.235 | 0.255 | 5.97 | 6.47 | |
| U | 0.000 | 0.050 | 0.00 | 1.27 | |
| V | 0.045 | | 1.15 | | |
| Z | | 0.080 | | 2.04 | |

| STYLE 1: | | STYLE 2: | | STYLE 3: | | STYLE 4: | |
|----------|-----------|-----------|-----------|----------|---------|----------|---------------------|
| PIN 1. | BASE | PIN 1. | BASE | PIN 1. | CATHODE | PIN 1. | MAIN TERMINAL 1 |
| 2. | COLLECTOR | 2. | EMITTER | 2. | ANODE | 2. | MAIN TERMINAL 2 |
| 3. | EMITTER | 3. | COLLECTOR | 3. | GATE | 3. | GATE |
| 4. | COLLECTOR | 4. | EMITTER | 4. | ANODE | 4. | MAIN TERMINAL 2 |
| STYLE 5: | | STYLE 6: | | STYLE 7: | | STYLE 8: | |
| PIN 1. | GATE | PIN 1. | ANODE | PIN 1. | CATHODE | PIN 1. | CATHODE |
| 2. | DRAIN | 2. | CATHODE | 2. | ANODE | 2. | ANODE |
| 3. | SOURCE | 3. | ANODE | 3. | CATHODE | 3. | EXTERNAL TRIP/DELAY |
| 4. | DRAIN | 4. | CATHODE | 4. | ANODE | 4. | ANODE |
| STYLE 9: | | STYLE 10: | | STYLE 11 | : | STYLE 12 | : |
| PIN 1. | GATE | PIN 1. | GATE | PIN 1. | DRAIN | PIN 1. | MAIN TERMINAL 1 |
| 2. | COLLECTOR | 2. | SOURCE | 2. | SOURCE | 2. | MAIN TERMINAL 2 |
| 3. | EMITTER | 3. | DRAIN | 3. | GATE | 3. | GATE |
| 4. | COLLECTOR | 4. | SOURCE | 4. | SOURCE | 4. | NOT CONNECTED |

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